



LEXAN™ Resin FXEMPX1L
Asia Pacific: COMMERCIAL

Opaque EXL, UV-Stabilized & light shielding capability, for portable electronics device enclosure application. Only available in white, grey and limited pastel colors. Consult CIC or PM for color availability & limitation.

TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	520	kgf/cm ²	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	460	kgf/cm ²	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	5	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	66	%	ASTM D 638
Tensile Modulus, 50 mm/min	20800	kgf/cm ²	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	810	kgf/cm ²	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	20200	kgf/cm ²	ASTM D 790
IMPACT			
Izod Impact, notched, 23°C	54	cm-kgf/cm	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	114	°C	ASTM D 648
PHYSICAL			
Density	1.3	g/cm ³	ISO 1183
Melt Volume Rate, MVR at 300°C/1.2 kg	15	cm ³ /10 min	ISO 1133



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PROCESSING PARAMETERS	TYPICAL VALUE	Unit
Injection Molding		
Drying Temperature	120	°C
Drying Time	3 - 4	hrs
Maximum Moisture Content	0.02	%
Melt Temperature	295 - 315	°C
Nozzle Temperature	290 - 310	°C
Front - Zone 3 Temperature	295 - 315	°C
Middle - Zone 2 Temperature	280 - 305	°C
Rear - Zone 1 Temperature	260 - 280	°C
Hopper Temperature	60 - 80	°C
Mold Temperature	70 - 95	°C